



PATENT APPLICATION

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kazunori SAKURAI et al.

Group Art Unit: 2824

Application No.: 09/843,924 ✓

Examiner: ^{Lutz} Douglas M. Menz

Filed: April 30, 2001

Docket No.: 109182

For: METHOD FOR FORMING BUMP, SEMICONDUCTOR DEVICE AND METHOD FOR MAKING THE SAME, CIRCUIT BOARD, AND ELECTRONIC DEVICE

AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the November 20, 2002 Office Action, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 7, lines 23-24, delete current paragraph and insert therefor:

11
Fig. 13(A) to Fig. 13(C) show a method for forming a bump according to an eighth embodiment of the present invention.

Page 8, lines 1-2, delete current paragraph and insert therefor:

12
Fig. 19 shows a method for forming a bump according to a tenth embodiment of the present invention.

Page 20, lines 20-27, delete current paragraph and insert therefor:

13
[0123] The resin layer 24 may be formed around the metal layers (the first metal layer 30 and the second metal layer 33) after the resist layer 20 is removed. Alternatively, the resist layer 20 may be left and used instead of the resin layer 24. In the latter case, the resist